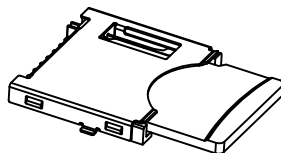
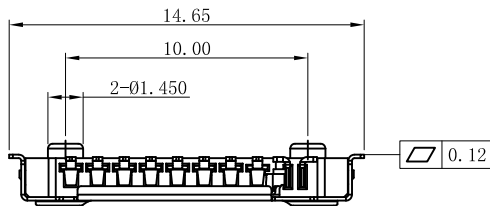


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2013/06/17	Jamie Zie

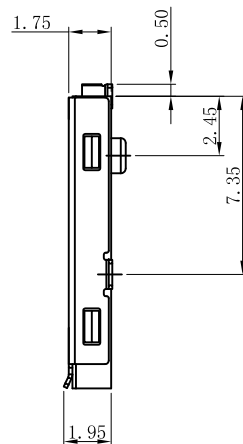
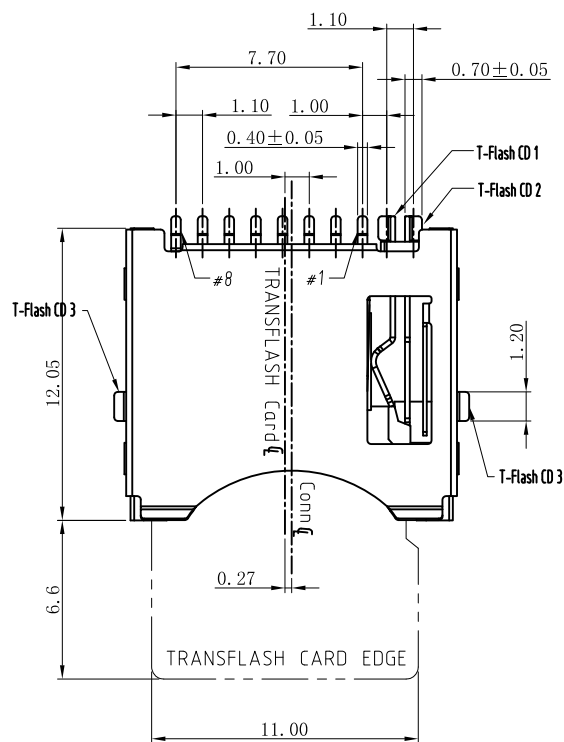


NOTES:

Current Rating: 0.5A AC, DC
Temperature Range: $-20^{\circ}\text{C} \sim +60^{\circ}\text{C}$
Contact Resistance: $40\text{m}\Omega_{\text{max}}$
Insulation Resistance: $1000\text{M}\Omega_{\text{min}}$
Withstanding Voltage: 500V
AC/minute
Material: LCP UL 94V-0

MATRIX PART NO:

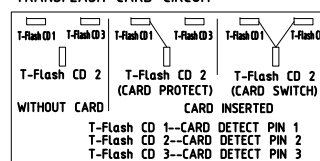
MMS - 02 - 01 - 08 - 17 - 07 - RS
Matrix SIM
01 : Push
02 : Non-Push
Planting
01:G/F
30:30u
Height
Pin number
06:6pin
08:8pin
RS:RoHS
HF:Hologen Free
Series Number



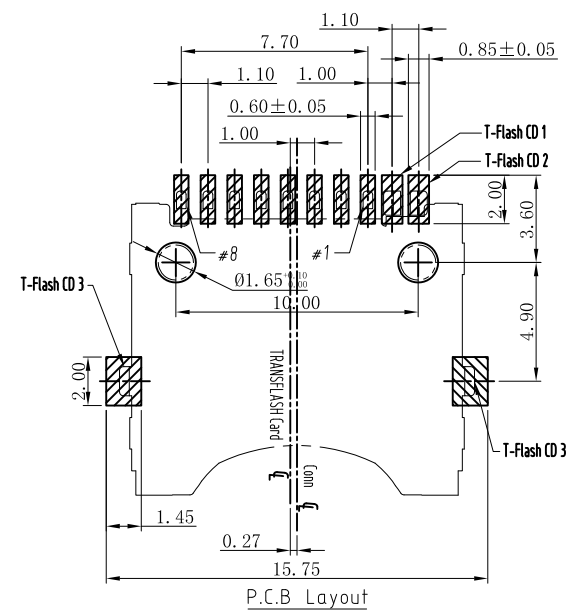
TRANSFLASH CARD PIN DESIGN(SD MODE)

Pin No.	Name	Type	Description
1#	DAT2	I/O/PP	Data Line (bit 2)
2#	CD/DAT3	I/O/PP	Card Detect/Data Line(Bit 3)
3#	CMD	PP	Command Response
4#	VDD	S	Supply Voltage
5#	CLK	I	Clock
6#	VSS	S	Supply Voltage Ground
7#	DAT0	I/O/PP	Data Line (bit 0)
8#	DAT# x	I/O/PP	Data Line (bit 1)

TRANSFLASH CARD CIRCUIT



Recommended P.C.B Layout(Top Side)



NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X. X X. XX X. XXX ANGLE: $\pm 3^{\circ}$		DESIGN BY : Jamie Zie	DATE : 2013/06/17	PART NAME: TF card no push outside welding 1.75H
CHECKED BY: Vicky Hsieh		DATE : 2013/06/17	PART NO.	MMS-02-01-08-17-07-RS
APPROVED BY1: Richard Hsieh		DATE : 2013/06/17	MOLD NO.	NA
APPROVED BY2: Richard Hsieh		DATE : 2013/06/17	DRAW NO.	
UNIT: mm [inch] SCALE: 1:1 SIZE: A4			SHEET NO.	1 OF 1